IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

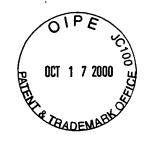
H14/C 10-25-00 Jawa:

In re aplication of

ANTHONY J. KONECNIET AL.

Serial No. 08/988,686 (TI-22166)

Filed December 11, 1997



For: METHOD AND SYSTEM FOR SELECTIVELY COUPLING A CONDUCTIVE MATERIAL TO A SURFACE OF A SEMICONDUCTOR DEVICE

Art Unit 2823

Examiner K. Eaton

Commissioner for Patents Washington, D. C. 20231

Sir:



AMENDMENT UNDER 37 C.F.R. 1.111

In response to the Office action dated Agust 30, 2000, please amend the above identified application as follows:

In the claims:

Amend claim 21 as follows:

21. (Amended) A method of fabricating an electronic device having a first <u>electrically</u> conductive structure electrically connected to a second <u>electrically</u> conductive structure situated over a semiconductor substrate, said method comprising the steps of:

forming said first electrically conductive structure;